# Claims

[c1]    A package and method for packaging optoelectric devices, comprising:

a generally rectangular package body comprising four sidewalls;

one or more than one thermal electrical cooler;

one or more than one platform on which opto-electronic devices and components to be disposed;

attaching the said thermal electrical cooler(s) on the sidewall(s) of the package box by applying epoxy or solder;

attaching the side(s) of the said platform(s) to the top of the thermal electrical coolers.

[c2]    The package and method of claim 1, wherein the package body has one or more than optical connector on its sidewall(s).

[c3]    The package and method of claim 1, wherein the package body has a top defining a generally rectangular opening and a closed bottom.

[c4]    The package body of claim 3 further comprising a lid hermetically scaled to the top of the package, the lid be-

ing free of connectors, leads, and mounting tabs.

[c5]    The package and method of claim 1, wherein the package box defining one generally rectangular top opening and another generally rectangular bottom opening.

[c6]    The package body of claim 5 further comprising a top lid and a bottom lid hermetically scaled to the top and the bottom of the box, the top and bottom lids being free of connectors, leads, and mounting tabs.

[c7]    The package and method of claim 1, wherein the package box is dual in-line package, in which a plurality of electronic leads extend the bottom of the said package.

[c8]    The package and method of claim 1, wherein the package box is butterfly box, in which a plurality of electronic leads extend one or more than one sidewall of the said package.

[c9]    The package and method of claim 1, wherein the thermal electrical cooler has a top plate and bottom plate and semiconductor elements sandwiched between the said top and bottom plates.

[c10]   The package and method of claim 1, wherein the package body has no or one or more than one radio-frequency connector on its sidewall(s) for high frequency

connection to or from the component(s) inside the box.